

Day	Session	Session Chairs	Time	Organization	Presentation Title	Presenting Author Names	
1	Registration		9:00-10:00		Registration and Welcome		
	Opening		10:00-10:10	ESA	Opening of the Symposium	Dr. Tommaso Ghidini	
	Keynote 1		10:10-10:40	Mbryonics	Challenges and Opportunities for Photonic Packaging and Integration	Mr. Alan Naughton	
	Emerging Technologies			10:40-11:05	Tekniker	Hybrid printed electronics in flexible substrates for space applications and advanced manufacturing methods	Dr. Borja Pozo
				11:05-11:30	AT&S AG	Novel Printed Circuit Board solutions for improved signal speed and minimized integrity losses	Mr. Erich Schläffer
				11:30-11:45		Coffee Break	
				11:45-12:10	Panasonic Industrial Devices Materials Europe GmbH	Panasonic advanced PCB and substrate materials	Ms. Monique Mayr
				12:10-12:35	Lukasiewicz-ITR	Development of embedded techniques and their influence on PCBs reliability	Mr. Marek Koscielski
				12:35-13:00	Adeon Technologies Bv	Turning Machine generated data into New Product Yield Analysis and Improvement	Mr. Vladi (Val) Kaplan
				13:00-14:00		Lunch	
	EEE Packaging			14:00-14:25	Alter Technology	Assessing Pseudo-hermeticity on COTS with Plastic Encapsulated Materials	Mr. Gonzalo Fernandez
				14:25-14:50	Lens R&D B.V.	Innovations in packaging for Sensensors	Mr. Johan Leijffens
				14:50-15:15	Aemtec GmbH	Validation of Wafer level solder bumping and Flip Chip packaging for Space applications	Mr. Daniel Lieske
				15:15-15:40		Coffee Break	
				15:40-16:05	Alter Technology	SIC Plastic High Temperature Diodes	Mr. Juan Moreno
	Lead-free Technologies			16:05-16:30	Micro Systems Engineering GmbH	From Wirebond to FlipChip - Towards a high mix, low volume toolbox for packaging in Europe	Dr. Thomas Triller
	Welcome Reception			16:30-16:55	nanoSPACE AG	Lead-free assembly technologies for telecom satellite equipment	Mr. Philippe Hersberger
	Keynote 2			17:00-19:00		Welcome Reception	
	2	Lead-free Technologies		9:00-9:30	IPC	Steps towards a resilient Silicon-to-System Ecosystem in Europe	Dr. Peter Tranitz
9:30-9:55				Elemca	EBSD of SAC solder joint to evaluate the lifetime of lead-free assemblies	Mr. Jeremie Dhennin	
9:55-10:20				ESA	Metallurgical characterization of Pb free alloys submitted to isothermal aging	Mr. Yassir Ben Dahou	
HDI Technologies				10:20-10:50		Coffee Break	
				10:50-11:15	TUBITAK UZAY Space Technology Research Institute	Lead Free Soldering Research in Microgravity	Mr. Hakan Asan
				11:15-11:40	ESA	Novel Surface Finishes for PCBs and Electronic Assemblies	Dr. Jussi Hokka
				11:40-12:05	Imec	Lessons learnt in qualifying high-density interconnect PCB technology for space applications	Mr. Maarten Cauwe
				12:05-12:30	Thales Alenia Space	European supply Chain for HDI and Embedded cutting edge substrate	Mr. Hugo Garcia
				13:00-14:00		Lunch	
				14:00-14:25	Systron (Cimulec Group)	High reliability HDI PCB for Space application	Mr. Julian Gerault
Materials for EEE packaging				14:25-14:50	Hytex	Typical defects in HDI PCBs, possible root causes and ECM testing	Mr. Poul Juul
				14:50-15:15	Rhp Technology GmbH	Advanced materials with tailored thermophysical properties for electronic cooling	Dr. Erich Neubauer
				15:15-15:40	Alter Technology	Capabilities and Significance of Thermomechanical Analysis in Space Applications	Ms. Beatriz Sarrion
	15:40-16:00				Coffee Break		
	16:00-16:25			Instituto de Microelectronica de Barcelona (IMB-CNM, CSIC)	High temperature aging tests of silver sintering materials used as die-attach layers	Ms. Emma Solà	
Social Dinner			16:25-16:50	Henkel	Innovative Semiconductor Packaging Materials for Next Gen RF Applications	Mr. Ruud de Wit	
Keynote 3			19:00-23:00		Social Dinner		
3	Modelling and Digitalization		9:00-9:30	EIPC	AI - Existential threat or opportunity for good	Mr. Alun Morgan	
			9:30-9:55	Imec	Life-time prediction of tin-lead (SnPb) soldered electronic assemblies under thermal cycling load	Mr. Chinmay Nawghane	
			9:55-10:20	Elastic-simulations GmbH	Cloud based virtual prototyping of electronic components	Dr. Harald Ziegelwanger	
			10:20-10:45	DSI Aerospace GmbH	PCB inspector-Tool for computed aided inspection and assembly of PCBs	Mr. András Szilágyi	
			10:45-11:10	ESA	Reliability modelling of EEE components, including PCBs and assemblies with reliability.space	Ms. Stephanie Bourbouse	
			11:10-11:30		Coffee Break		
	Testing and Characterization			11:30-11:55	Thales Alenia Space	New monitoring methodology for COTS BGA assembly verification	Dr. Emile Leynia De La Jarrige
				11:55-12:20	CNES	In-situ monitoring of solder damage with X-ray laminography for board level reliability	Mr. Pierre Roumanille
				12:20-12:45	Private company	New technological approach for soldering technology based on the argumentation of thermodynamic impacts in soldering processes	Mr. Landulf Skoda
				12:45-13:10	NPL	Measuring the effects of pressure on partial discharge inception and degradation in conformal coatings, printed circuit boards and gel materials	Mr. Martin Wickham
Closing			13:10-13:15	ESA	Closing and End of Symposium		